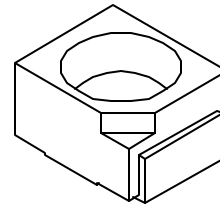
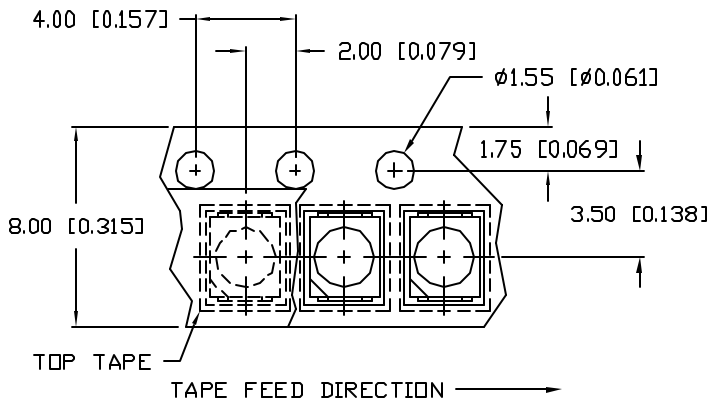
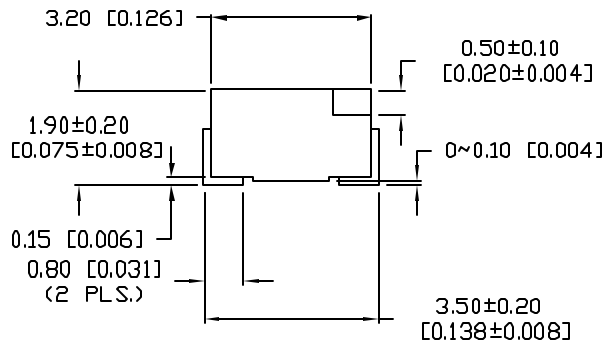
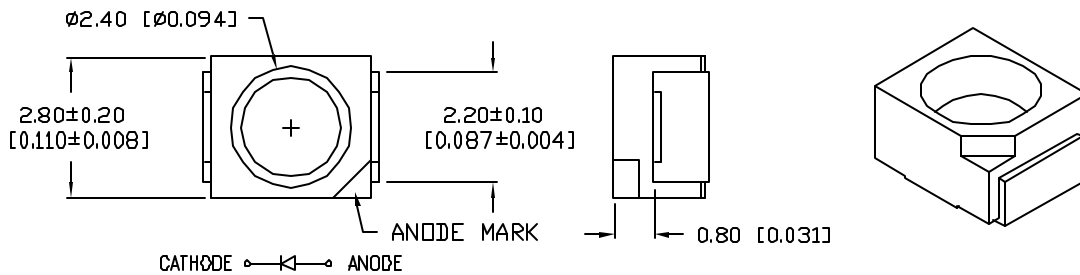
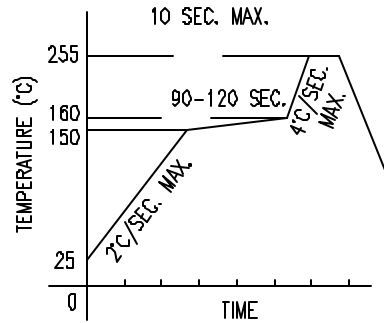


UNCONTROLLED DOCUMENT

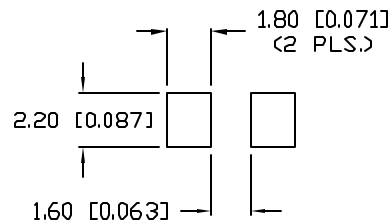


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



REPLACES PART #: SML-LX2832SRC(-TR)

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=^{+DECIMAL PRECISION}_{-0.00}, MAX.=^{+0.00}_{-DECIMAL PRECISION}

PART NUMBER
SML-LX2832SRC-TR

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10804.	11.2.01
B	E.C.N. #10967.	3.14.03
C	E.C.N. #11148.	2.8.05

ELECTRO-OPTICAL CHARACTERISTICS T_A=25°C I_F=20mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V _F	
REVERSE VOLTAGE	4.0			V _R	I _R =100μA
AXIAL INTENSITY	40	100		mcd	I _F =20mA
VIEWING ANGLE			120	2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	200	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	110	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* t<10μs

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

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REV.
C

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SML-LX2832SRC-TR

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2.8mm x 3.2mm SURFACE MOUNT LED WITH REFLECTOR,
660nm SUPER RED LED, WATER CLEAR LENS,
2,000 PIECES PER TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 1.11.01
			PAGE: 1 OF 1
			SCALE: N/A